

Electronic Patent Application Fee Transmittal

Application Number:	10685312			
Filing Date:	14-Oct-2003			
Title of Invention:	INTERPOSER SUBSTRATES WITH MULTI-SEGMENT INTERCONNECT SLOTS, SEMICONDUCTOR DIE PACKAGES INCLUDING SAME, SEMICONDUCTOR DICE FOR USE THEREWITH AND METHODS OF FABRICATION			
First Named Inventor/Applicant Name:	Blaine J. Thurgood			
Filer:	Joseph A. Walkowski/Mary Hancock			
Attorney Docket Number:	2269-5520.1US (02-0676.01			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	790	790
Total in USD (\$)				790